

IN THE CLAIMS

Please amend the claims as follows:

1. (Currently amended) A leadframe comprising:

an outer frame with a plurality of sides surrounding a region of the leadframe on which a semiconductor chip is to be mounted;

a die pad on which the semiconductor chip is to be mounted; and

a plurality of leads each having land portions and connections, the land portions each having an upper surface serving as a bonding pad to be connected with a metal wiring and a lowermost part serving as an external terminal, the connections each being devoid of its lower part so as to be thinner than the land portion and being provided between the outer frame and the land portions, between the land portions associated with each other in each lead, and between the land portions and the die pad,

wherein the die pad and the outer frame are connected to each other via the land portions and the connections there exists no member that functions as a suspension lead during plastic encapsulation.

2. (Original) The leadframe according to claim 1, wherein the lowermost parts of the land portions are substantially identical in shape in plan view and are arranged in a lattice pattern.

3. (Original) The leadframe according to claim 1, wherein three or more rows of the lowermost parts of the land portions are arranged along each side of the outer frame.

4. (Original) The leadframe according to claim 1, wherein the plurality of leads include a lead that is connected to one side of the outer frame and is connected to the other lead that is connected to the other side of the outer frame adjacent to the one side thereof.

5. (Original) A leadframe comprising:

an outer frame with a plurality of sides surrounding a region of the leadframe on which a semiconductor chip is to be mounted;

a die pad having a thin portion that is provided along the peripheral section of the main body of the die pad and that is devoid of its lower part, and a plurality of heat dissipating terminals each protruded downward from the lower surface of the thin portion; and

a plurality of leads each having land portions and connections, the land portions each having an upper surface serving as a bonding pad to be connected with a metal wiring and a lowermost part serving as an external terminal, the connections each being devoid of its lower part so as to be thinner than the land portion and being provided between the outer frame and the land portions, between the land portions associated with each other in each lead, and between the land portions and the heat dissipating terminals.

6. (Original) The leadframe according to claim 5, wherein the land portions and the heat dissipating terminals are substantially identical in shape in plan view and are arranged in a lattice pattern.

7. (Original) The leadframe according to claim 5, wherein the land portions and the heat dissipating terminals are arranged at substantially fixed pitch intervals in at least one direction.

8. (Original) The leadframe according to claim 5, wherein three or more rows of the land portions are arranged along each side of the outer frame.

9. (Original) The leadframe according to claim 5, wherein there exists no member that functions as a suspension lead during plastic encapsulation.

10-23. (Cancelled)